

NOT RECOMMENDED FOR NEW DESIGN - NO ALTERNATE PART



DMN90H8D5HCT

N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BVDSS	Rds(on)	Package	I _D T _C = +25°C
900V	$7\Omega@V_{GS} = 10V$	TO220AB (Type TH)	2.5A

Description

This new generation MOSFET features low on-resistance and fast switching, making it ideal for high efficiency power management applications.

Applications

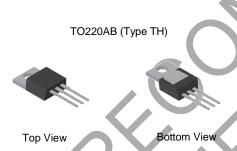
- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

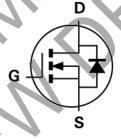
Features

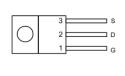
- Low Input Capacitance
- High BV_{DSS} Rating for Power Application
- Low Input/Output Leakage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Case: TO220AB
- Case Material: Molded Plastic, "Green" Molding Compound, UL Flammability Classification Rating 94V-0
- Terminals: Matte Tin Finish Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (23)
- Terminal Connections: See Diagram Below
- Weight: 1.85 grams (Approximate)







Equivalent Circuit

Top View Pin Out Configuration

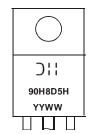
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN90H8D5HCT	TO220AB (Type TH)	50 Pieces/Tube

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



☐ H=Manufacturer's Marking
90H8D5H = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Last Two Digits of Year (ex: 20 = 2020)
WW or WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	900	V		
Gate-Source Voltage	V_{GSS}	±30	V		
Continuous Drain Current, V _{GS} = 10V	Steady State	$T_C = +25$ °C $T_C = +100$ °C	I _D	2.5 1.5	А
Maximum Body Diode Forward Current (Note 5)	Is	3	Α		
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)	I _{DM}	3	Α		
Avalanche Current, L = 60mH (Note 7)	las	1.8	Α		
Avalanche Energy, L = 60mH (Note 7)	Eas	97	mJ		
Peak Diode Recovery dv/dt	dv/dt	3.3	V/ns		

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	PD	125 50	W
Thermal Resistance, Junction to Ambient (Note 6)		R _θ JA	50	°C/W
Thermal Resistance, Junction to Case		Rejc		C/VV
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BVDSS	900			V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS		1	1	μΑ	V _{DS} = 900V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_		100	nA	$V_{GS} = \pm 30V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	3.0	4	5.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	RDS(ON)	_	5.5	7	Ω	V _G S = 10V, I _D = 1A	
Diode Forward Voltage	VsD	Ī	0.84	1.2	V	$V_{GS} = 0V$, $I_{S} = 2A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	Ciss		470	_		V _{DS} = 25V, f = 1.0MHz, V _{GS} = 0V	
Output Capacitance	Coss		45	_	pF		
Reverse Transfer Capacitance	Crss		0.6	_			
Gate Resistance	Rg		1.2	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$	
Total Gate Charge	Qg	_	7.9	_		7001/ 1 04	
Gate-Source Charge	Qgs	_	2.5	_	nC	$V_{DD} = 720V, I_{D} = 2A,$ $V_{GS} = 10V$	
Gate-Drain Charge	Qgd	_	2.9	_			
Turn-On Delay Time	tD(ON)	_	16	_		$V_{DD} = 450V, R_G = 25\Omega, I_D = 2A,$ $V_{GS} = 10V$	
Turn-On Rise Time	t _R	_	21	_	ns		
Turn-Off Delay Time	tD(OFF)	_	17.6	_	115		
Turn-Off Fall Time	tF	_	17	_			
Body Diode Reverse Recovery Time	t _{RR}	_	375	_	ns	$dI/dt = 100A/\mu s$, $V_{DS} = 100V$,	
Body Diode Reverse Recovery Charge	Qrr	_	2.9	_	μC	I _F = 2A	

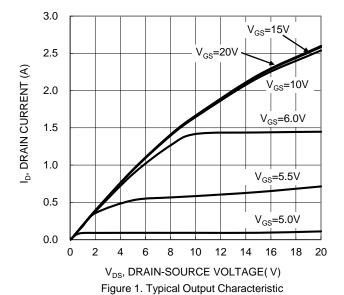
Notes:

^{5.} Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

^{7.} Guaranteed by design. Not subject to production testing.
8. Short duration pulse test used to minimize self-heating effect.







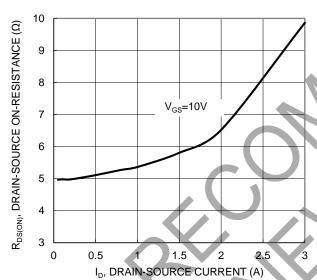


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

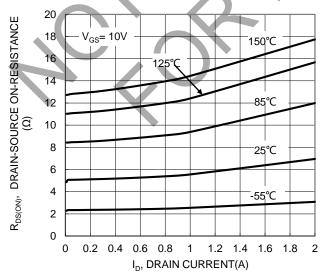


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

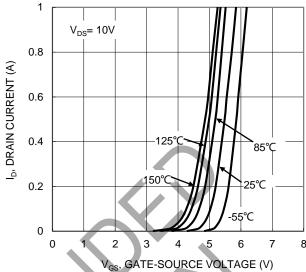


Figure 2. Typical Transfer Characteristic

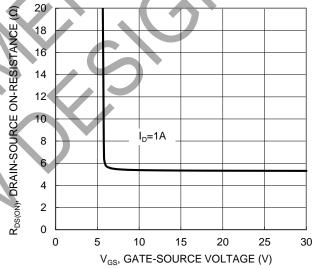


Figure 4. Typical Transfer Characteristic

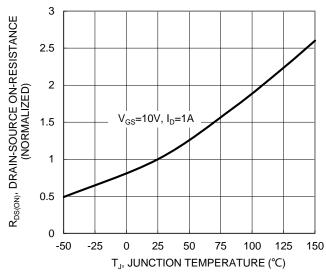


Figure 6. On-Resistance Variation with Junction Temperature





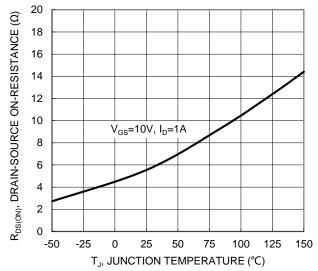


Figure 7. On-Resistance Variation with Junction Temperature

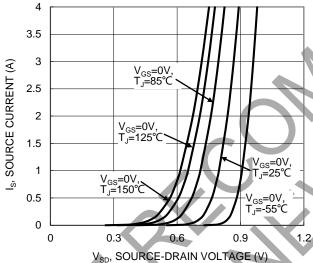


Figure 9. Diode Forward Voltage vs. Current

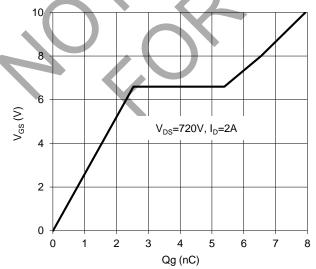


Figure 11. Gate Charge

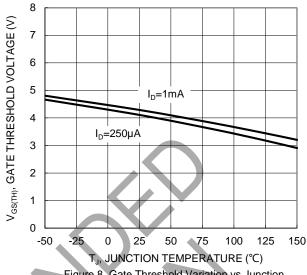
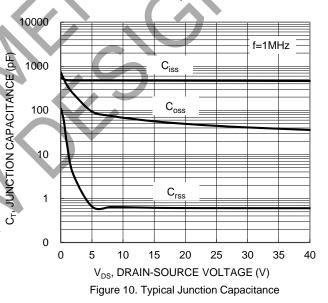


Figure 8. Gate Threshold Variation vs Junction Temperature



10 $R_{DS(ON)}$ Limited P_W=10µs $P_w = 100 \mu s$ DRAIN CURRENT (A) P_W=10ms $T_{J(Max)}$ =150°C P_w=100ms T_C=25°C Single Pulse DUT on infinite heatsink V_{GS}=10V 0.1 10 100 1000 V_{DS}, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area



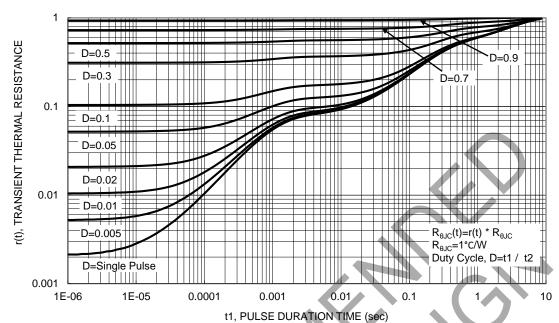


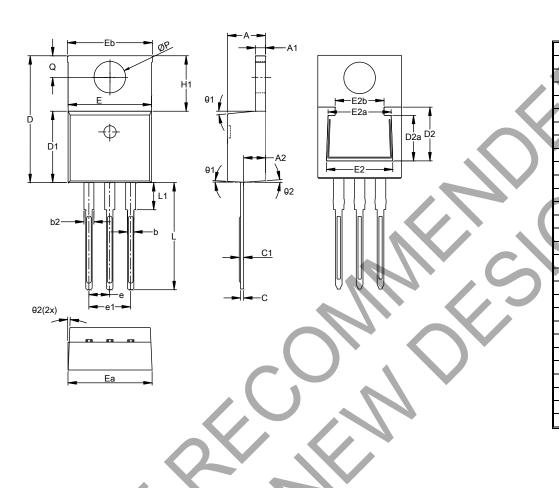
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO220AB (Type TH)



TO220AB (Type TH)						
Dim	Min	Max	Тур			
Α	4.27	4.87	4.57			
A1	1.12	1.42	1.27			
A2	2.39	2.99	2.69			
b	0.70	1.01	0.81			
b2	1.17	1.50	1.27			
С	0.30	0.53	0.38			
с1	0.38	0.72	0.56			
D	14.60	15.40	15.00			
D1	8.40	9.00	8.70			
D2	5.33	6.63	6.33			
D2a	4.54	5.84	5.54			
e	2.54 BSC					
e1		5.08 BSC				
E	9.88	10.50	10.16			
Ea	9.90	10.45	10.10			
Eb	9.90	10.65	10.25			
E2	7.06	8.36	8.06			
E2a	6.67	7.97	7.67			
E2b	4.94	6.24	5.94			
H1	5.70	6.65	6.30			
L	13.00	13.80	13.40			
L1	-	4.10	3.75			
Q	2.50	2.99	2.74			
ØΡ	3.70	3.99	3.84			
θ1	4°	10°	7°			
θ2	θ2 0° 6° 3°					
All Dimensions in mm						



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